

#4/Election  
4/15/03  
C.P.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
PATENT APPLICATION

In re Application of:

Xiaoju Wu

Docket: TI-33227

Serial No.: 10/013,088

Art Unit: 2814

Filed: 12/07/2001

Examiner: A. Mai

For: METHOD OF MANUFACTURING AND STRUCTURE OF  
SEMICONDUCTOR DEVICE WITH FIELD OXIDE STRUCTURE

FAX RECEIVED

APR 14 2003

TECHNOLOGY CENTER 2800

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4-14-03

Jackie McBride  
Jackie McBride

ELECTION

Sir:

In response to the Examiner's restriction requirement (Paper-No. 3) mailed April 4, 2003, Applicant hereby elects to pursue Group II, Claims 10-18 for examination purposes.

Respectfully submitted,

Yingsheng Tung  
Yingsheng Tung  
Attorney for Applicants  
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<table border="1"> <tr> <td colspan="2">NAME OF INVENTOR(S): <b>Xiaoju Wu</b></td> <td colspan="2">RECEIPT DATE &amp; SERIAL NO.: <b>Serial No.: 10/013,088</b></td> </tr> <tr> <td colspan="2">TITLE OF INVENTION: <b>Method of Manufacturing and Structure of Semiconductor Device with Field...</b></td> <td colspan="2"><b>Filing Date: 12/07/2001</b></td> </tr> <tr> <td>TI FILE NO.: <b>TI-33227</b></td> <td>DEPOSIT ACCT. NO.: <b>20-0668</b></td> <td colspan="2"></td> </tr> <tr> <td colspan="2">FAXED: <b>04/14/2003</b> DUE: <b>05/03/2003</b> ATTY/SEC'Y: <b>YT/jsm</b></td> <td colspan="2"></td> </tr> </table>		NAME OF INVENTOR(S): <b>Xiaoju Wu</b>		RECEIPT DATE & SERIAL NO.: <b>Serial No.: 10/013,088</b>		TITLE OF INVENTION: <b>Method of Manufacturing and Structure of Semiconductor Device with Field...</b>		<b>Filing Date: 12/07/2001</b>		TI FILE NO.: <b>TI-33227</b>	DEPOSIT ACCT. NO.: <b>20-0668</b>			FAXED: <b>04/14/2003</b> DUE: <b>05/03/2003</b> ATTY/SEC'Y: <b>YT/jsm</b>			
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